SPECIFICATIONS

Customer	
Product Name	**Thin Film RF Inductor**
Sunlord Part Number	**SDCL0402Q-P02 Series**
Customer Part Number	

[☒New Released, ☐Revised] **SPEC No.: SDCL0126250004**

【This SPEC is total 13 pages.】

【ROHS Compliant Parts】

Approved By	**Checked By**	**Issued By**

Shenzhen Sunlord Electronics Co., Ltd.

Address: Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110
Tel: 0086-755-29832333 Fax: 0086-755-82269029 E-Mail: sunlord@sunlordinc.com

【For Customer approval Only】 Date:________________________

Qualification Status: ☐ Full ☐ Restricted ☐ Rejected

Approved By	Verified By	Re-checked By	Checked By

Comments:

____

【Version change history】

Rev.	Effective Date	Changed Contents	Change reasons	Approved By
01	Sep.26,2025	New release	/	Xiaolan Han

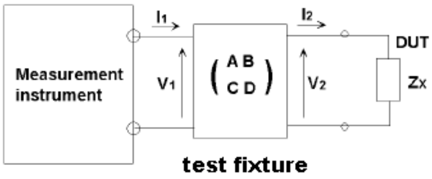
Caution

All products listed in this specification are developed, designed and intended for use in general electronics equipment. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require especially high reliability, or whose failure, malfunction or trouble might directly cause damage to society, person, or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below. Please contact us for more details if you intend to use our products in the following applications.

1. Aircraft equipment
2. Aerospace equipment
3. Undersea equipment
4. nuclear control equipment
5. military equipment
6. Power plant equipment
7. Medical equipment
8. Transportation equipment (automobiles, trains, ships,etc.)
9. Traffic signal equipment
10. Disaster prevention / crime prevention equipment
11. Applications of similar complexity or with reliability requirements comparable to the applications listed in the above

Measuring Method of Inductance

a. Residual elements and stray elements of test fixture can be described by F-parameter as shown in the following:



$$\begin{bmatrix} V_1 \\ I_1 \end{bmatrix} = \begin{bmatrix} A & B \\ C & D \end{bmatrix} \begin{bmatrix} V_2 \\ I_2 \end{bmatrix}$$

$$\begin{bmatrix} V_1 \\ I_1 \end{bmatrix} = \begin{bmatrix} AV_2 + BI_2 \\ CV_2 + DI_2 \end{bmatrix}$$

Measured open impedance: $Zom = \frac{A}{C}$

Measured short impedance: $Zsm = \frac{B}{D} \approx -Zsc$ (when uses short chip to short)

Measured short ship impedance: Zsc

Measured value: $Zxm = V_1/I_1$

Impedance of DUT: $Zx = V_2/I_2$

b. The relation between Zx and Zom, Zsm, Zxm is shown in the following:

$$Zx = \frac{V_2}{I_2} = \frac{D}{A} * \frac{\frac{V_1}{I_1} - \frac{B}{D}}{1 - \frac{V_1}{I_1} * \frac{C}{A}} = \frac{D}{A} * \frac{Zxm - \frac{B}{D}}{1 - Zxm * \frac{C}{A}} = \frac{D}{A} * \frac{Zxm - Zsm}{1 - Zxm / Zom}$$

c. Lx should be calculated with the following equation:

$$Lx = \frac{\mathrm{Im}(Zx)}{2\pi f} = \frac{\mathrm{Im}(Zxm + Zsc)}{2\pi f} = \frac{\mathrm{Im}(Zxm)}{2\pi f} + \frac{\mathrm{Im}(Zsc)}{2\pi f} = Lxm + Lsc$$

Lxm：Measured chip inductor inductance
Lsc：Measured short chip inductance
Lx：Nominal Inductance of chip inductor

Compensation Value（Lsc）of Short Chip

Series	Compensation Value
SDCL0402Q-P02	0.19nH

1. Scope

This specification applies to SDCL0402Q-P02 series of thin film radio frequency inductor.

2. Product Description and Identification (Part Number)

2.1 Description:

SDCL0402Q-P02 series of thin film radio frequency inductor.

2.2 Product Identification (Part Number)

SDCL	0402	Q	XXX	□	◎	02
①	②	③	④	⑤	⑥	⑦

① Type	
SDCL	Super Q Ceramic Chip Inductor

② External Dimensions (L X W) (mm)	
0402 [01005]	0.4 X 0.2

③ Applications and Characteristics Code	
Q	Chip Thickness=0.23mm

④ Nominal Inductance	
Example	Example
3N9	3N9
10N	10N

⑤ Inductance Tolerance	
B、C、S	±0.1、±0.2、±0.3nH
G、H、J	±2%、±3%、±5%

⑥ Packing	
P	Plastic Tape Carrier Package

⑦ Serial Code	
01	Internal code

3. Electrical Characteristics

Please refer to **Appendix A** (Page11-12).

3.1 Operating and storage temperature range (individual chip without packing): -55℃ ~+125℃.

3.2 Storage temperature range (packaging conditions): -10℃~+40℃ and RH 70% (Max.).

4. Shape and Dimensions

4.1 Dimensions and recommended PCB pattern for reflow soldering: See **Fig.4-1**, **Fig.4-2** and **Table 4-1**.

4.2 Structure: See **Fig. 4-3** and **Fig. 4-4**.

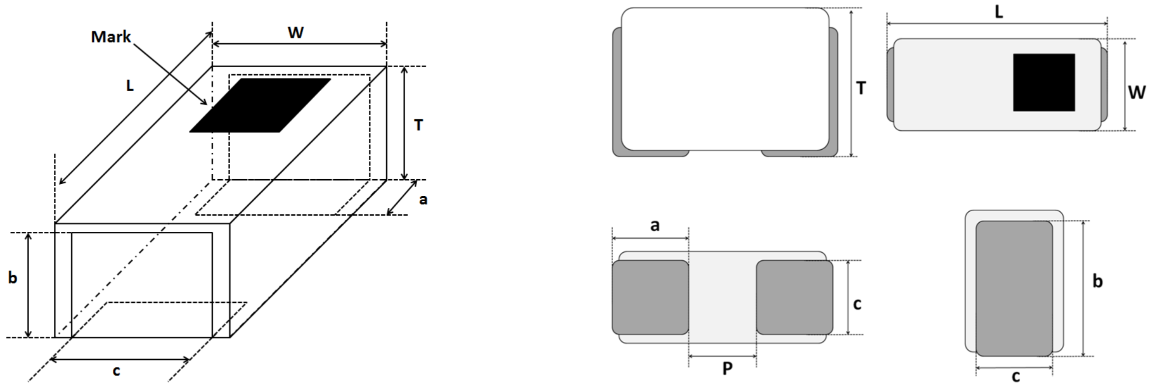


Fig. 4-1

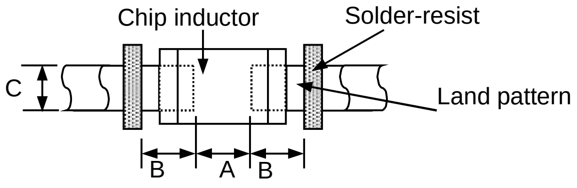
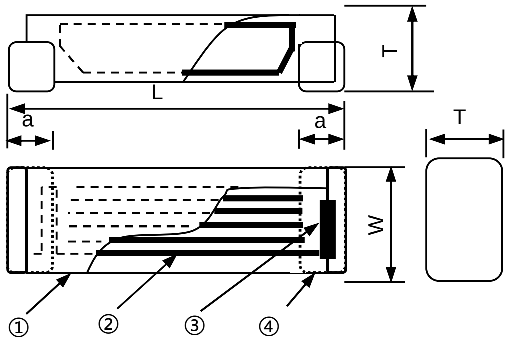


Fig. 4-2

[Table 4-1]

Unit: mm [inch]

Type	L	W	T	a	b	c	A	B	C
0402 [01005]	0.4±0.02 [.016±.0008]	0.2±0.02 [.008±.0008]	0.23±0.02 [.009±.0008]	0.11±0.03 [.005±.0010]	0.20±0.03 [.005±.0010]	0.17±0.03 [.006±.0010]	0.15~0.19	0.18~0.22	0.18~0.22



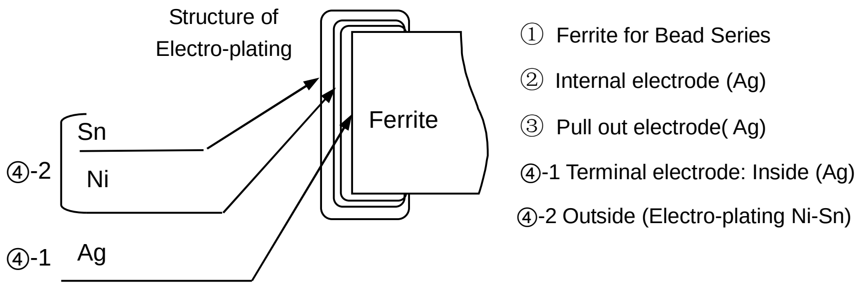


Fig. 4-4

[Fig 4-3]

[Fig 4-4]

4.3 Material information: See Table 4-2.

[Table 4-2]

Code	Part Name	Material Name
①	Ceramic Body	Ceramic Powder
②	Inner Coils	Silver Paste
③	Pull-out Electrode (Ag)	Silver Paste
④-1	Terminal Electrode: Inside Ag	Silver Paste
④-2	Electro-Plating: Ni/Sn plating	Plating Chemicals

4.4 Soldering Notice: The surface with the mark should be on the two beside when soldering

5. Test and Measurement Procedures

5.1 Test Conditions

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- a. Ambient Temperature: 20±15℃
- b. Relative Humidity: 65±20%
- c. Air Pressure: 86 KPa to 106 KPa

5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:

- a. Ambient Temperature: 20±2℃
- b. Relative Humidity: 65±5%
- c. Air Pressure: 86KPa to 106 KPa

5.2 Visual Examination

- a. Inspection Equipment: 60 X magnifier

5.3 Electrical Test

5.3.1 DC Resistance (DCR)

- a. Refer to Appendix A.
- b. Test equipment (Analyzer): Super Accuracy Milliohmmeter-HP4338B or equivalent.

5.3.2 Inductance (L)

- a. Refer to Appendix A.
- b. Test equipment: Super Accuracy RF Impedance /Material Analyzer-E4991A+16198A or equivalent.
- c. Test signal: -20dBm or 50mV
- d. Test frequency refers to Appendix A.
- e. Short bar residual inductance=0.19nH

5.3.3 Q Factor (Q)

- a. Refer to Appendix A.
- b. Test equipment: Super Accuracy RF Impedance /Material Analyzer-E4991A+16198A or equivalent.
- c. Test signal: -20dBm or 50mV
- d. Test frequency refers to Appendix A.

5.3.4 Self-Resonant Frequency (SRF)

- a. Refer to Appendix A.
- b. Test equipment: Agilent 8719ES or equivalent.
- c. Test signal: -20 dBm or 50 mV

5.3.5 Rated Current

- a. Refer to Appendix A.
- b. Test equipment (see Fig. 5.3.5-1): Electric Power, Electric current meter, Thermometer.
- c. Measurement method (see Fig. 5.3.5-1):
  1. Set test current to be 0 mA.

2. Measure initial temperature of chip surface.
3. Gradually increase voltage and measure chip temperature for corresponding current.

d. Definition of Rated Current(Ir): Ir is direct electric current as chip surface temperature rose just 20℃ against chip initial surface temperature(Ta) (see Fig. 5.3.5-2).

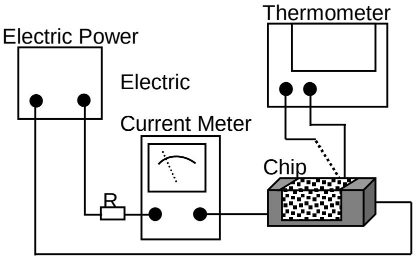


Fig. 5.3.5-1

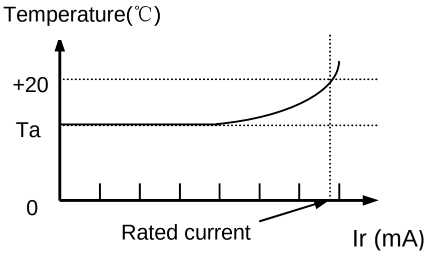


Fig. 5.3.5-2

5.4 Reliability Test

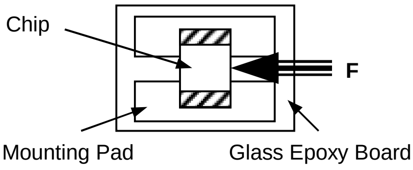
<table>
<tr><th>Items</th><th>Requirements</th><th>Test Methods and Remarks</th></tr>
<tr><td>5.4.1
Terminal
Strength</td><td>No removal or split of the termination or other defects shall occur.


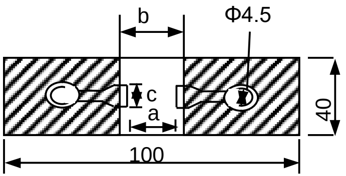
Fig.5.4.1-1</td><td>① Solder the inductor to the testing jig (glass epoxy board shown in Fig. 5.4.1-1) using leadfree solder. Then apply a force in the direction of the arrow.
② 1N force for SDCL0402Q-P02 series.
③ Keep time: 10±1s
④ Speed: 1.0mm/s.</td></tr>
<tr><td>5.4.2
Resistance to
Flexure</td><td>No visible mechanical damage.
<table><tr><td colspan="4">Unit: mm [inch]</td></tr><tr><td>Type</td><td>a</td><td>b</td><td>c</td></tr><tr><td>0402[01005]</td><td>0.18</td><td>0.8</td><td>0.2</td></tr></table>


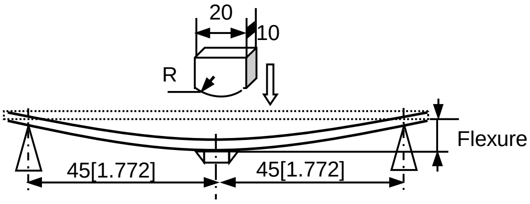
Fig. 5.4.2-1</td><td>① Solder the inductor to the test jig (glass epoxy board shown in Fig. 5.4.2-1) Using a leadfree solder. Then apply a force in the direction shown Fig. 5.4.2-2.
② Flexure: 2mm.
③ Pressurizing Speed: 0.5mm/sec.
④ Keep time: 30 sec.


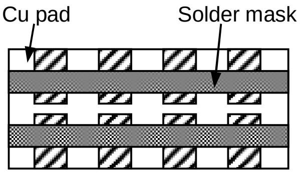
Fig. 5.4.2-2</td></tr>
<tr><td>5.4.3
Vibration</td><td>① No visible mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.


Fig. 5.4.3-1</td><td>① Solder the inductor to the testing jig (glass epoxy board shown in Fig. 5.4.3-1) using leadfree solder.
② The inductor shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz.
③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours).</td></tr>
<tr><td>5.4.4
Dropping</td><td>① No visible mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.</td><td>Drop chip inductor 10 times on a concrete floor from a height of 100 cm.</td></tr>
<tr><td>5.4.5
Temperature</td><td>Inductance change should be within ±10% of initial value measuring at 20℃.</td><td>Temperature range: SDCL0402Q-P02: -55℃ to +125℃,
Reference temperature: +20℃</td></tr>
<tr><td>5.4.6
Solderability</td><td>① No visible mechanical damage.
② Wetting shall exceed 95% coverage.</td><td>① Solder temperture:240±2℃
② Duration: 3 sec.
③ Solder: Sn/3.0Ag/0.5Cu.
④ Flux: 25% Resin and 75% ethanol in weight.</td></tr>
<tr><td>5.4.7</td><td>① No visible mechanical damage.</td><td>① Solder temperature: 260±3℃</td></tr>
</table>

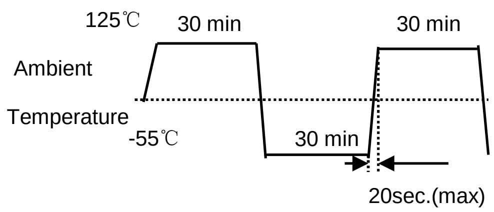
<table>
<tr>
<td>Resistance to Soldering Heat</td>
<td>② Wetting shall exceed 75% coverage.
③ Inductance change: Within ±10%.
④ Q factor change: Within ±20%.</td>
<td>② Duration: 5 sec.
③ Solder: Sn/3.0Ag/0.5Cu.
④ Flux: 25% Resin and 75% ethanol in weight.
⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
<tr>
<td>5.4.8
Thermal Shock</td>
<td>① No mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.


Fig. 5.4.8-1</td>
<td>① Temperature, Time: (See **Fig. 5.4.8-1**)
SDCL0402Q-02: -55℃for 30±3 min→125℃ for 30±3min,
② Transforming interval: Max. 20 sec.
③ Tested cycle: 100 cycles.
④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
<tr>
<td>5.4.9
Resistance to Low Temperature</td>
<td>① No mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.</td>
<td>① Temperature: -55±2℃,
② Duration: 1000^{+24} hours.
③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
<tr>
<td>5.4.10
Resistance to Super Temperature</td>
<td>① No mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.</td>
<td>① Temperature: 125±2℃,
② Duration: 1000^{+24} hours.
③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
<tr>
<td>5.4.11
Damp Heat (Steady States)</td>
<td>① No visible mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.</td>
<td>① Temperature: 60±2℃
② Humidity: 90% to 95% RH.
③ Duration: 1000^{+24} hours.
④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
<tr>
<td>5.4.12
Loading Under Damp Heat</td>
<td>① No visible mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.</td>
<td>① Temperature: 60±2℃
② Humidity: 90% to 95% RH.
③ Duration: 1000^{+24} hours.
④ Applied current: Rated current.
⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
<tr>
<td>5.4.13
Loading at Super Temperature (Life Test)</td>
<td>① No visible mechanical damage.
② Inductance change: Within ±10%.
③ Q factor change: Within ±20%.</td>
<td>① Temperature: 125±2℃,
② Duration: 1000^{+24} hours.
③ Applied current: Rated current.
④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td>
</tr>
</table>

6. Packaging and Storage

6.1 Packaging

Tape Carrier Packaging:

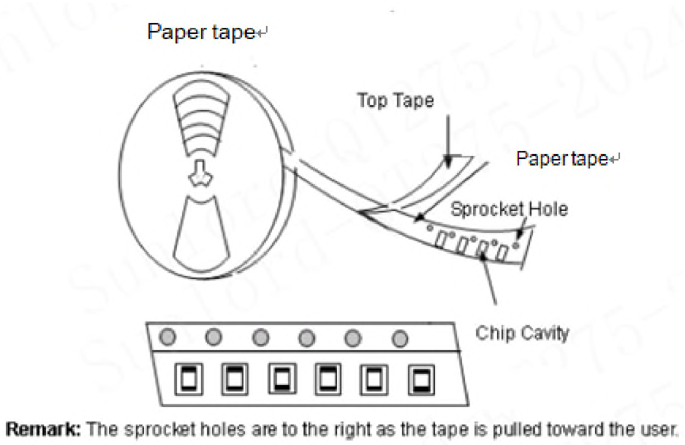
Packaging code: P

a Tape carrier packaging are specified in attached figure **Fig.6.1-1~3**

b Tape carrier packaging quantity please see the following table:

Type	0402[01005]
Thickness (mm)	0.2±0.05
Tape	Plastic Tape
Quantity	30K

(1) Taping Drawings (Unit: mm)



Remark: The sprocket holes are to the right as the tape is pulled toward the user.

Fig. 6.1-1

(2) Taping Dimensions (Unit: mm)

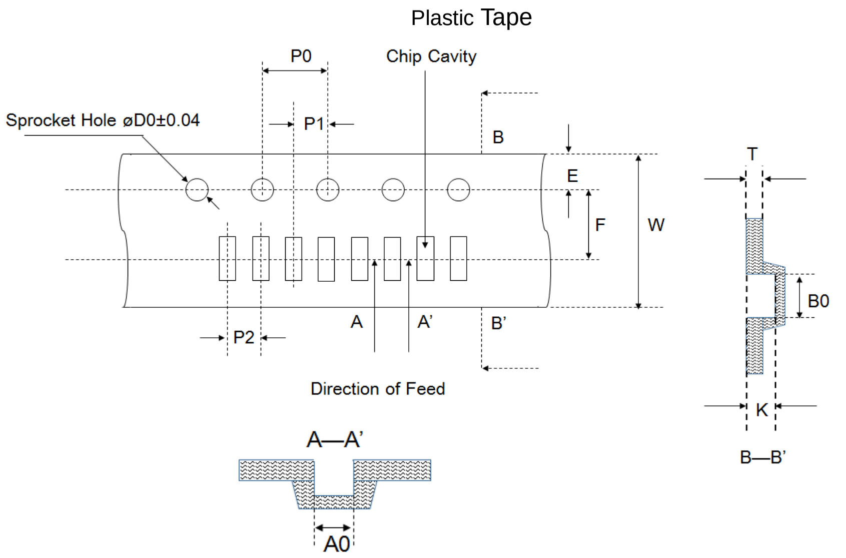


Fig. 6.1-2

[Table 6-1-1] Unit:mm

Type	A0	B0	T	W	K	P0	P1	P2	D0	F	E
0402	0.24± 0.02	0.44± 0.02	0.2± 0.05	4.0± 0.05	0.27± 0.02	2.0± 0.04	1.0± 0.03	1.0± 0.03	0.80± 0.04	1.8± 0.03	0.9± 0.05

(3) Reel Dimensions (Unit: mm)

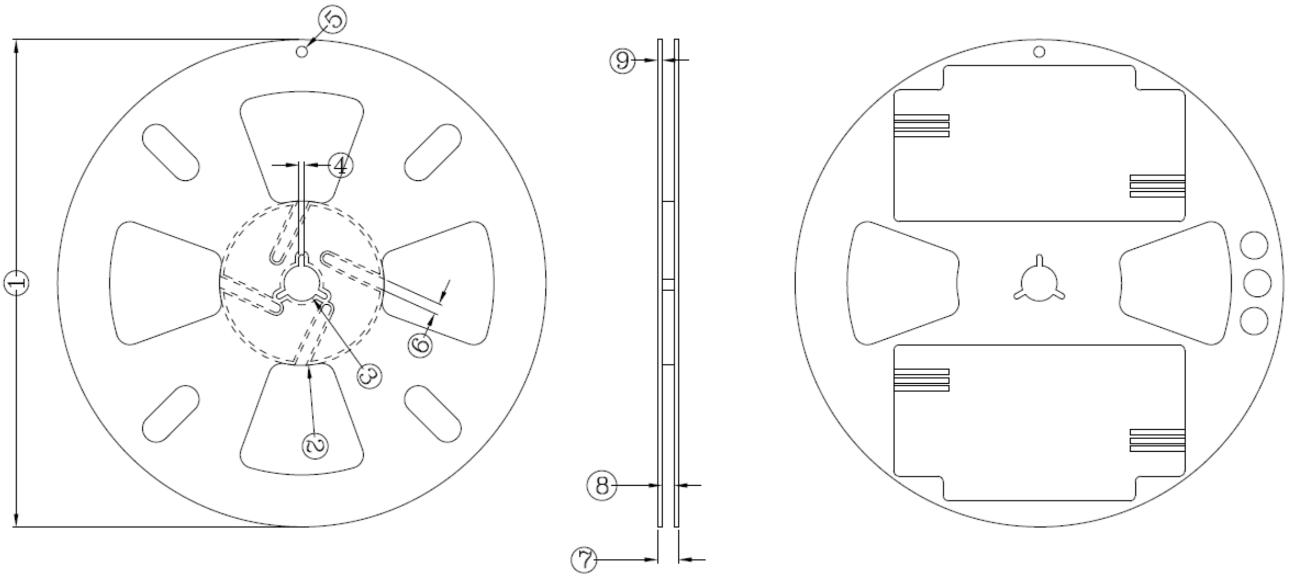


Fig. 6.1-3

[Table 6-1-2] Unit:mm

a)	b)	③	④	⑤	⑥	⑦	⑧	⑨
178±1.0	60±1.0	13±0.3	2.0±0.5	4±0.2	4±0.5	7.5±1	4.5±0.5	1.5±0.3

6.2 Storage

6.2.1 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Package must be stored at 40℃ or less and 70% RH or less.

6.2.2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H_2S).

6.2.3 Packaging material may be deformed if package are stored where they are exposed to heat of direct sunlight.

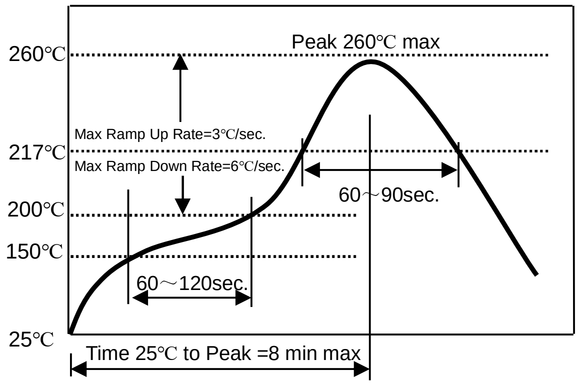
6.2.4 Minimum packages, such as polyvinyl heat-seal packages shall not be opened until they are used. If opened, use the reels as soon as possible.

6.2.5 Solderability specified in Clause 5.4.6 shall be guaranteed for 6 months from the date of delivery on condition that they are 0stored at the environment specified in **Clause 3** .For those parts, which passed more than 6 months shall be checked solder-ability before use.

7. Recommended Soldering Technologies

7.1 Reflowing Profile:

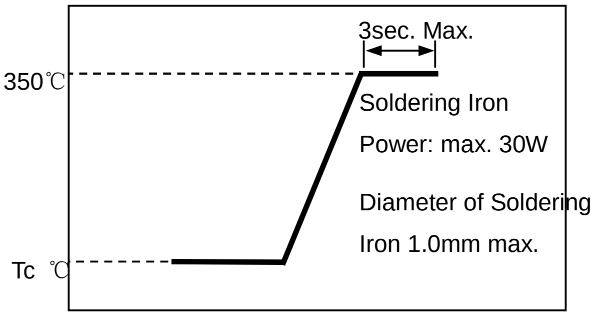
7.1.1 Preheat condition: 150 ~200℃/60~120sec.
7.1.2 Allowed time above 217℃: 60~90sec.
7.1.3 Max temp: 260℃
7.1.4 Max time at max temp: 10sec.
7.1.5 Solder paste: Sn/3.0Ag/0.5Cu
7.1.6 Allowed Reflow time: 2x max



[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

7.2 Iron Soldering Profile

7.2.1 Iron soldering power: Max.30W
7.2.2 Pre-heating: 150 ℃ / 60sec.
7.2.3 Soldering Tip temperature: 350℃Max.
7.2.4 Soldering time: 3sec Max.
7.2.5 Solder paste: Sn/3.0Ag/0.5Cu
7.2.6 Max.1 times for iron soldering



[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]

Appendix A: Electrical Characteristics (SDCL0402Q-P02 Series of Inductors)

SDCL0402Q-P02 **Series of Inductor**

Part Number	Inductance	Min. Quality Factor	L, Q Test Freq .L/Q	Typical Q @ Freq. (GHz)					Min .Self-resonant Frequency	Max. DC Resistance	Max .Rated Current	Thickness
				0.5	0.8	1.8	2.0	2.4				
Units	nH	-	MHz	-					MHz	Ω	mA	mm [inch]
Symbol	L	Q	Freq	Q					S.R.F	DCR	Ir	T
SDCL0402Q0N3BP02	0.3	14	500	/	/	/	/	/	17000	0.05	900	0.23±0.02 [.009±.0008]
SDCL0402Q0N4BP02	0.4	14	500	/	/	/	/	/	17000	0.07	900	
SDCL0402Q0N5BP02	0.5	14	500	/	/	/	/	/	17000	0.07	900	
SDCL0402Q0N6BP02	0.6	14	500	20	25	36	38	45	16600	0.09	700	
SDCL0402Q0N7BP02	0.7	14	500	20	25	36	38	45	16600	0.09	700	
SDCL0402Q0N8BP02	0.8	14	500	20	25	37	39	46	16600	0.12	600	
SDCL0402Q0N9BP02	0.9	14	500	19	25	36	38	45	15500	0.18	450	
SDCL0402Q1N0BP02	1.0	14	500	19	25	36	38	45	15500	0.18	450	
SDCL0402Q1N1BP02	1.1	14	500	19	25	36	38	45	15500	0.20	400	
SDCL0402Q1N2BP02	1.2	14	500	19	24	35	37	44	15500	0.20	400	
SDCL0402Q1N3BP02	1.3	14	500	19	24	35	37	44	15500	0.20	400	
SDCL0402Q1N4BP02	1.4	14	500	19	25	36	38	45	15000	0.21	400	
SDCL0402Q1N5BP02	1.5	14	500	19	24	35	37	43	15000	0.21	400	
SDCL0402Q1N6BP02	1.6	14	500	19	23	35	36	43	15000	0.27	350	
SDCL0402Q1N7BP02	1.7	14	500	19	24	35	36	43	15000	0.27	350	
SDCL0402Q1N8BP02	1.8	14	500	19	24	35	37	44	13000	0.27	350	
SDCL0402Q1N9BP02	1.9	14	500	19	24	35	37	44	12000	0.28	350	
SDCL0402Q2N0BP02	2.0	14	500	19	25	35	38	45	11000	0.28	350	
SDCL0402Q2N1BP02	2.1	14	500	19	25	35	37	44	11000	0.28	350	
SDCL0402Q2N2BP02	2.2	14	500	19	25	35	37	43	10500	0.32	300	
SDCL0402Q2N3BP02	2.3	14	500	19	24	34	36	43	10500	0.32	300	
SDCL0402Q2N4BP02	2.4	14	500	19	25	37	39	46	10500	0.36	300	
SDCL0402Q2N5BP02	2.5	14	500	19	24	35	36	43	10000	0.36	300	
SDCL0402Q2N6BP02	2.6	14	500	19	24	35	36	43	10000	0.36	300	
SDCL0402Q2N7BP02	2.7	14	500	19	24	37	39	43	9500	0.41	300	
SDCL0402Q2N8BP02	2.8	14	500	19	24	37	40	46	9500	0.41	300	
SDCL0402Q2N9BP02	2.9	14	500	19	24	36	39	45	9500	0.41	300	
SDCL0402Q3N0BP02	3.0	14	500	19	25	36	38	45	9500	0.46	300	
SDCL0402Q3N1BP02	3.1	14	500	19	25	35	37	43	9000	0.46	300	
SDCL0402Q3N2BP02	3.2	14	500	19	24	35	37	44	9000	0.46	300	
SDCL0402Q3N3BP02	3.3	14	500	19	25	36	38	45	9000	0.46	300	
SDCL0402Q3N4BP02	3.4	14	500	19	24	35	38	44	9000	0.46	300	
SDCL0402Q3N5BP02	3.5	14	500	19	25	36	38	45	8700	0.5	250	
SDCL0402Q3N6BP02	3.6	14	500	19	24	35	37	44	8700	0.5	250	
SDCL0402Q3N7BP02	3.7	14	500	19	24	35	37	44	8700	0.5	250	
SDCL0402Q3N8BP02	3.8	14	500	19	24	34	36	42	8700	0.5	250	
SDCL0402Q3N9BP02	3.9	14	500	18	23	33	35	39	8700	0.54	200	
SDCL0402Q4N0BP02	4.0	14	500	18	23	33	35	40	8000	0.54	200	
SDCL0402Q4N1BP02	4.1	14	500	18	23	33	35	40	7500	0.54	200	
SDCL0402Q4N2BP02	4.2	14	500	18	23	34	36	41	7000	0.54	200	

Part Number	Inductance	Min. Quality Factor	L, Q Test Freq .L/Q	Typical Q @ Freq. (GHz)					Min .Self-resonant Frequency	Max. DC Resistance	Max .Rated Current	Thickness
				0.5	0.8	1.8	2.0	2.4				
Units	nH	-	MHz	-					MHz	Ω	mA	mm [inch]
Symbol	L	Q	Freq	Q					S.R.F	DCR	Ir	T
SDCL0402Q4N3HP02	4.3	14	500	18	22	33	35	40	7000	0.54	200	0.23±0.02 [.009±.0008]
SDCL0402Q4N7HP02	4.7	14	500	18	23	34	36	42	7000	0.72	180	
SDCL0402Q5N1HP02	5.1	14	500	17	22	32	34	37	6600	0.72	180	
SDCL0402Q5N6HP02	5.6	14	500	17	22	31	33	36	6100	0.72	180	
SDCL0402Q6N2HP02	6.2	14	500	17	22	32	33	38	6000	1.0	160	
SDCL0402Q6N8HP02	6.8	14	500	17	21	30	32	35	5700	1.0	160	
SDCL0402Q7N5HP02	7.5	14	500	16	20	29	31	34	5500	1.2	150	
SDCL0402Q8N2HP02	8.2	14	500	17	21	30	32	35	5300	1.2	150	
SDCL0402Q9N1HP02	9.1	14	500	16	20	29	32	35	5000	1.5	140	
SDCL0402Q10NHP02	10	14	500	16	20	29	31	34	4500	1.5	140	
SDCL0402Q11NHP02	11	14	500	16	21	28	30	31	4200	1.6	130	
SDCL0402Q12NHP02	12	14	500	16	20	27	28	29	4000	1.6	130	
SDCL0402Q13NHP02	13	12	500	15	18	25	26	27	3800	1.8	130	
SDCL0402Q15NHP02	15	12	500	15	18	24	25	25	3500	2.0	120	
SDCL0402Q16NHP02	16	12	500	15	18	24	25	25	3500	2.0	120	
SDCL0402Q18NHP02	18	9	500	11	15	18	20	19	3000	2.2	110	
SDCL0402Q20NHP02	20	9	500	11	15	18	20	19	2700	2.6	100	
SDCL0402Q22NHP02	22	9	500	11	14	17	20	18	2300	3.0	100	

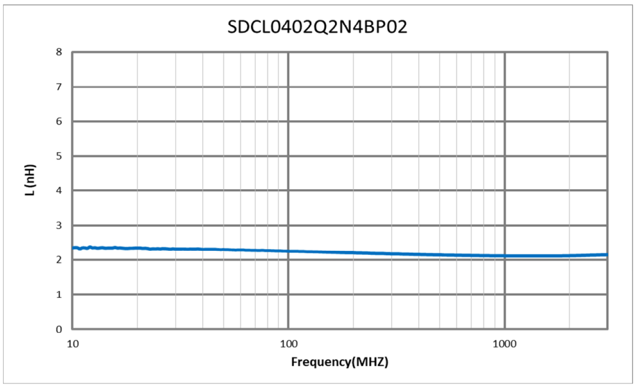
Note: □: Please specify the inductance tolerance. For L≤4.2nH, choose B=±0.1nH, C=±0.2nH or S=±0.3nH; For 4.2nH＜L＜5.6nH, choose, H=±3%, J=±5%. or S=±0.3nH；For L≥5.6nH, choose, H=±3%, J=±5%

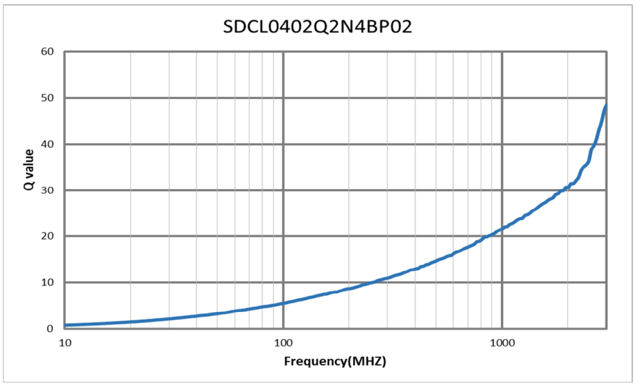
TYPICAL ELECTRICAL CHARACTERISTICS

Inductance-Frequency Characteristics(Typ.)

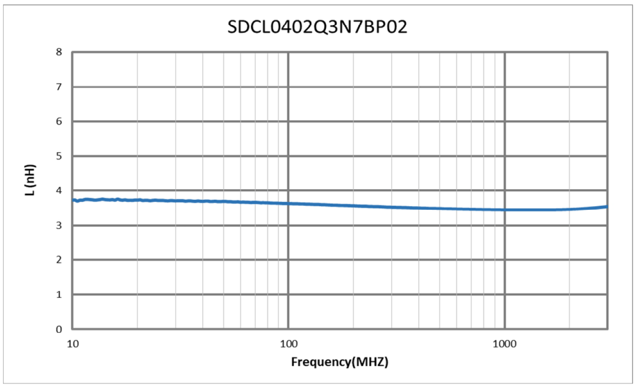
Q-Frequency Characteristics(Typ.)

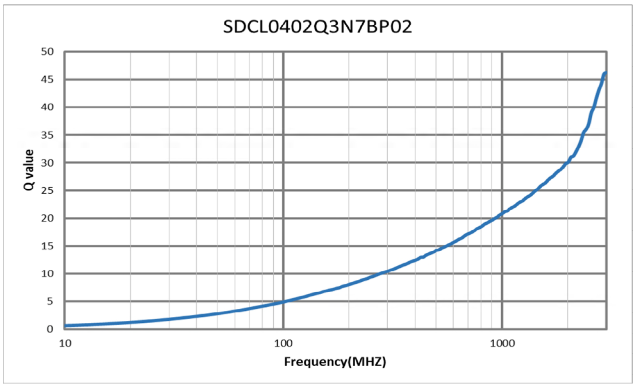
SDCL0402Q2N4BP02



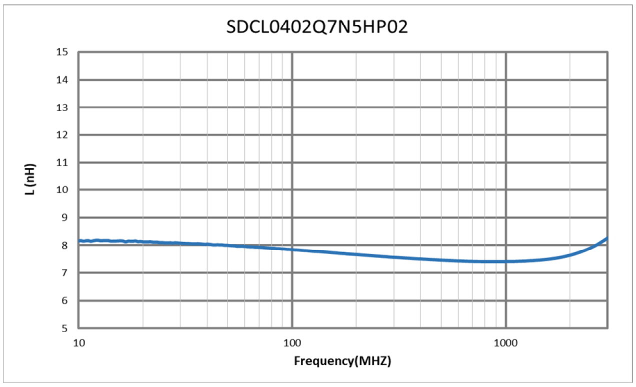


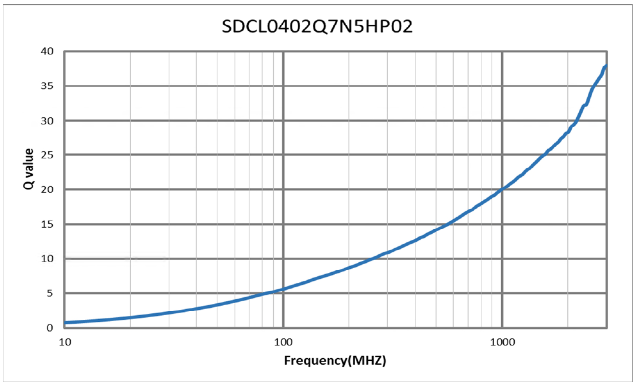
SDCL0402Q3N7BP02





SDCL0402Q7N5HP02





SDCL0402Q15NHP02